



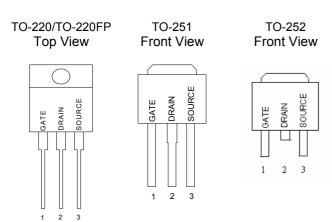
GENERAL DESCRIPTION

This advanced high voltage MOSFET is designed to withstand high energy in the avalanche mode and switch efficiently. This hew high energy device also offers a drain-to-source diode with fast recovery time. Designed for high voltage, high speed switching applications such as power supplies, converters, power motor controls and bridge circuits. ◆

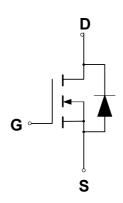
FEATURES

- Higher Current Rating
- ◆ Lower Rds(on)
- ◆ Lower Capacitances
- Lower Total Gate Charge
 - Tighter VSD Specifications
- Avalanche Energy Specified

PIN CONFIGURATION



SYMBOL



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS

Rating			Value	Unit
Drain to Current — Continuous		I _D	3.6	Α
- Puls	ed	I_{DM}	10.8	
Gate-to-Source Voltage	- Continue	V _{GS}	±30	V
Total Power Dissipation	TO-251/TO-252	P _D	48	W
	TO-220		80	
	TO-220FP		27	
Derate above 25°ℂ	TO-251/TO-252		0.38	W/°C
	TO-220		0.7	
	TO-220FP		0.21	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to 150	$^{\circ}\!\mathbb{C}$
Single Pulse Drain-to-Source Avalanche Energy $-$ T _J = 25 $^{\circ}$ C		Eas	4-	
$(V_{DD} = 100V, V_{GS} = 10V, I_L = 3A, L = 10mH, R_G = 25\Omega)$			45	mJ
Thermal Resistance — Junction to Case TO-251/TO-252			2.6	°C/W
	TO-220		1.5	
	TO220FP		4.6	
 Junction to Ambient TO-251/TO-252 			120	
	TO-220, TO-220FP		62.5	
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds		TL	260	$^{\circ}\!\mathbb{C}$





ORDERING INFORMATION

Part Number	Package
GPT04N60GN220*	TO-220
GPT04N60GN220FP*	TO-220 Full Package
GPT04N60GN251*	TO-251
GPT04N60GN252*	TO-252

^{*}Note: G: Suffix for Pb Free Product

ELECTRICAL CHARACTERISTICS

Unless otherwise specified, $T_J = 25^{\circ}C$.

				GPT04N60		
Chai	Symbol	Min	Тур	Max	Units	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	600			V	
$(V_{GS} = 0 \text{ V}, I_D = 250 \ \mu \text{ A})$						
Drain-Source Leakage Current		I _{DSS}			1	uA
$(V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V})$						
Gate-Source Leakage Current-Fo	orward	I _{GSSF}			100	nA
$(V_{gsf} = 30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate-Source Leakage Current-Re	everse	I_{GSSR}			100	nA
$(V_{gsr} = -30 \text{ V}, V_{DS} = 0 \text{ V})$						
Gate Threshold Voltage		$V_{GS(th)}$	2.5	3.5	4.5	V
$(V_{DS} = V_{GS}, I_D = 250 \ \mu A)$						
Static Drain-Source On-Resistance (V _{GS} = 10 V, I _D = 2.0A) *		R _{DS(on)}			2.6	Ω
Forward Transconductance (V _{DS}	= 15 V, I _D = 2.0 A) *	g FS		4		S
Input Capacitance	$(V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	C _{iss}		553		pF
Output Capacitance	$(V_{DS} - 25 \text{ V}, V_{GS} - 0 \text{ V},$ f = 1.0 MHz)	C_{oss}		52. 2		pF
Reverse Transfer Capacitance	1 – 1.0 Wil 12)	C _{rss}		4. 2		pF
Turn-On Delay Time	// - 200 \/ L - 4.0 A	t _{d(on)}		18. 7		ns
Rise Time	$(V_{DD} = 300 \text{ V}, I_D = 4.0 \text{ A},$ $V_{GS} = 10 \text{ V}.$	t _r		16		ns
Turn-Off Delay Time	$V_{GS} = 10 \text{ V},$ $R_{G} = 9.1\Omega) *$	t _{d(off)}		33. 6		ns
Fall Time	NG - 9.112)	t _f		17. 1		ns
Total Gate Charge	()/ - 400 \/ I - 40 A	Qg		13. 4		nC
Gate-Source Charge	$(V_{DS} = 480 \text{ V}, I_D = 4.0 \text{ A},$ $V_{GS} = 10 \text{ V})^*$	Q _{gs}		3		nC
Gate-Drain Charge	v _{GS} = 10 v)	Q _{gd}		6. 3		nC
SOURCE-DRAIN DIODE CHARA	ACTERISTICS	·		•	•	•
Forward On-Voltage(1)	(1 - 4 0 0	V _{SD}			1.5	V
Forward Turn-On Time	$(I_S = 4.0 \text{ A},$	t _{on}		**		ns
Reverse Recovery Time	rse Recovery Time d _{IS} /d _t = 100A/µs)			220		ns

^{*} Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%

^{**} Negligible, Dominated by circuit inductance





TYPICAL ELECTRICAL CHARACTERISTICS

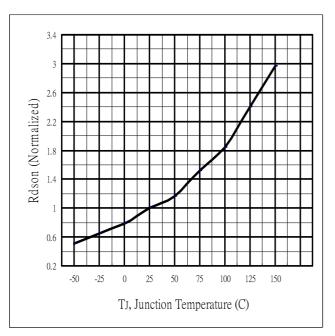


Fig 1. On-Resistance Variation with vs. Temperature

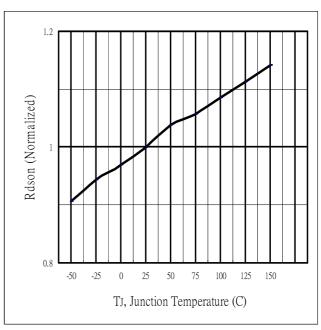


Fig.2 Breakdown Voltage Variation vs. Temperature

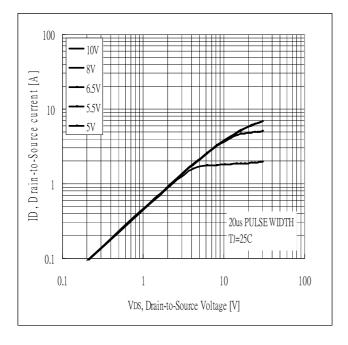


Fig 3. Typical Output Characteristics

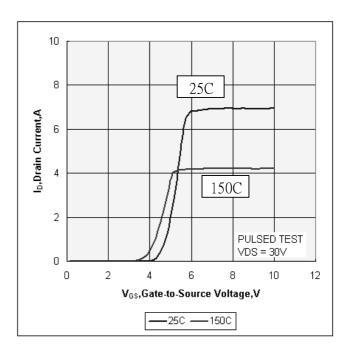


Fig 4. Typical Transfer Characteristics







Power Field Effect Transistor

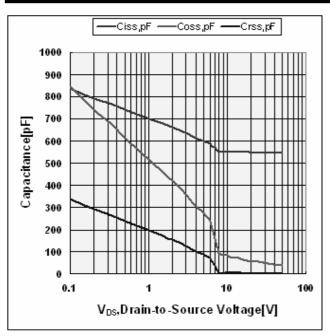


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

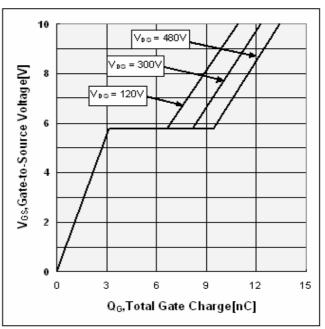


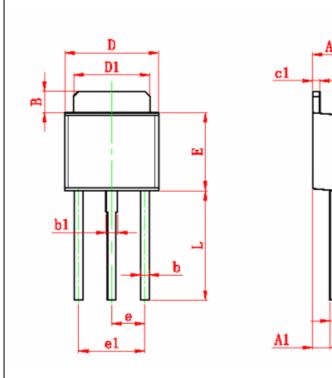
Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage





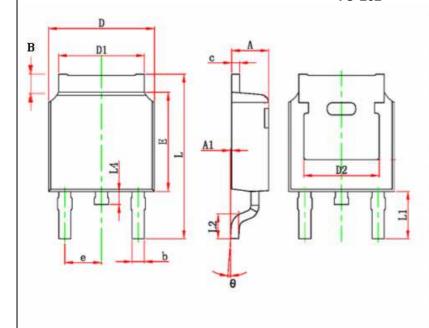
PACKAGE DIMENSION





Symbol	Dimensions In Millimeters		
	Min.	Max	
A	2.10	2.50	
A1	0.90	1.35	
В	0.90	1.65	
Ъ	0.45	0.75	
b1	0.65	0.95	
С	0.40	0.60	
c1	0.40	0.60	
D	6.30	6.80	
D1	5.00	5.50	
E	5.40	6.30	
е	2.3 TYP.		
e1	4.40	4.80	
L	7.40	8.00	

TO-252



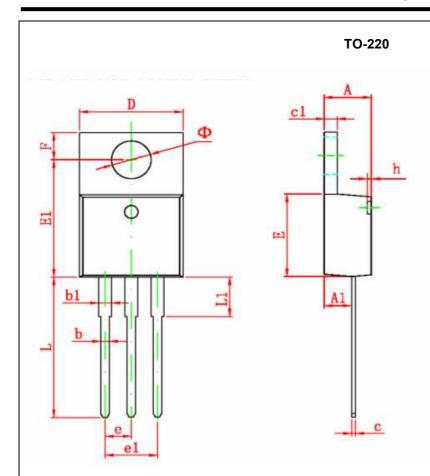
Carra le a l	Dimensions	In Millimeters	
Symbol	Min.	Max	
Α	2.10	2.50	
A1	0.90	1.35	
В	0.90	1.65	
Ъ	0.45	0.90	
С	0.40	0.60	
D	6.30	6.80	
D1	5.00	5.50	
D2	4.83 TYP.		
E	5.90	6.30	
e	2.3 TYP.		
L	9.30	10.50	
L2	1.20	1.80	
L4	0.60	1.00	
θ	0.00	10.00	





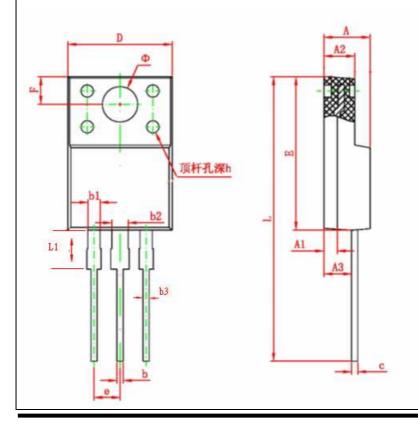
GPT04N60

POWER FIELD EFFECT TRANSISTOR



Cross had	Dimensions In Millimeters		
Symbol	Min.	Max	
Α	4.40	4.80	
A1	2.10	2.84	
Ъ	0.71	0.91	
b1	1.17	1.37	
С	0.30	0.60	
c1	1.17	1.47	
D	9.40	10.60	
Е	8.40	9.60	
е	2.54 TYP.		
e1	4.90	5.60	
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	12.50	14.00	
L1	3.50	4.00	

TO-220FP



Symbol	Dimensions In Millimeters		
	Min.	Max	
Α	3.80	4.70	
A1	1.3 REF.		
A2	2.20	3.20	
A3	2.10	3.20	
Ъ	0.30	0.95	
b1	1.00	1.75	
b2	1.00	1.75	
b3	0.50	0.80	
С	0.30	0.90	
D	9.90	10.40	
E	14.60	16.20	
е	2.54 TYP.		
F	3.00 REF.		
Φ	3.50 REF.		
h	0.00	0.30	
L	28.00	30.00	
Ll	3.20	3.55	



GPT04N60

IMPORTANT NOTICE

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